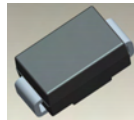


1.5A SURFACE MOUNT FAST RECOVERY RECTIFIER
Features

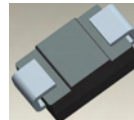
- Glass Passivated Die Construction
- Fast Recovery Time For High Efficiency
- Surge Overload Rating to 50A Peak
- Ideally Suited for Automated Assembly
- **Lead Free Finish/RoHS Compliant (Note 1)**
- **Green Molding Compound (No Halogen and Antimony) (Note 2)**

Mechanical Data

- Case: SMA/SMB
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminals: Lead Free Plating (Matte Tin Finish). Solderable per MIL-STD-202, Method 208
- Polarity: Cathode Band or Cathode Notch
- Marking Information: See Page 3
- Ordering Information: See Page 3
- SMA Weight: 0.065 grams (approximate)
- SMB Weight: 0.09 grams (approximate)



Top View



Bottom View

Maximum Ratings @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load.
For capacitance load, derate current by 20%.

Characteristic	Symbol	RS2 A/AA	RS2 B/BA	RS2 D/DA	RS2 G/GA	RS2 J/JA	RS2 K/KA	RS2 M/MA	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage (Note 6)	V_{RRM} V_{RWM} V_R	50	100	200	400	600	800	1000	V
RMS Reverse Voltage	$V_{R(RMS)}$	35	70	140	280	420	560	700	V
Average Rectified Output Current @ $T_T = 120^\circ\text{C}$	I_O	1.5							A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I_{FSM}	50							A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance, Junction to Terminal (Note 3)	$R_{\theta JT}$	20	$^\circ\text{C/W}$
Operating and Storage Temperature Range	T_J, T_{STG}	-65 to +150	$^\circ\text{C}$

Electrical Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	RS2 A/AA	RS2 B/BA	RS2 D/DA	RS2 G/GA	RS2 J/JA	RS2 K/KA	RS2 M/MA	Unit
Forward Voltage @ $I_F = 1.5\text{A}$	V_{FM}	1.3							V
Peak Reverse Current @ $T_A = 25^\circ\text{C}$ at Rated DC Blocking Voltage (Note 6) @ $T_A = 125^\circ\text{C}$	I_{RM}	5.0 200							μA
Reverse Recovery Time (Note 5)	t_{rr}	150			250		500		ns
Typical Total Capacitance (Note 4)	C_T	30							pF

- Notes:
1. EU Directive 2002/95/EC (RoHS). All applicable RoHS exemptions applied. Please visit our website at http://www.diodes.com/quality/lead_free.html.
 2. Product manufactured with Data Code 0924 (week 24, 2009) and newer are built with Green Molding Compound.
 3. Thermal Resistance: Junction to terminal, unit mounted on PC board with 5.0 mm^2 (0.013 mm thick) copper pads as heat sink.
 4. Measured at 1.0MHz and applied reverse voltage of 4.0V DC.
 5. Reverse recovery test conditions: $I_F = 0.5\text{A}$, $I_R = 1.0\text{A}$, $I_{rr} = 0.25\text{A}$. See Figure 5.
 6. Short duration pulse test used to minimize self-heating effect.

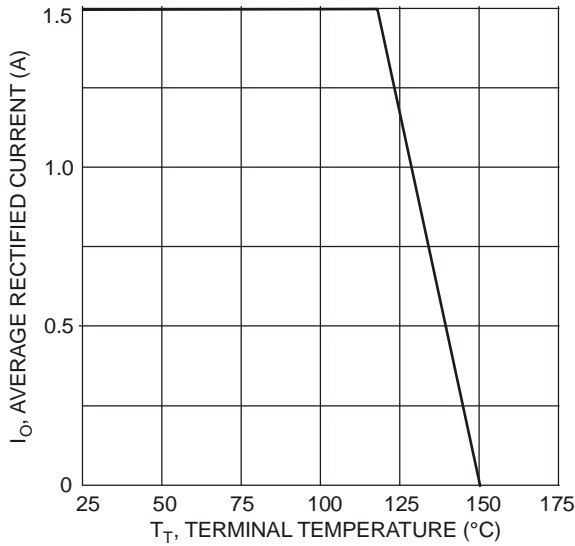


Fig. 1 Forward Current Derating Curve

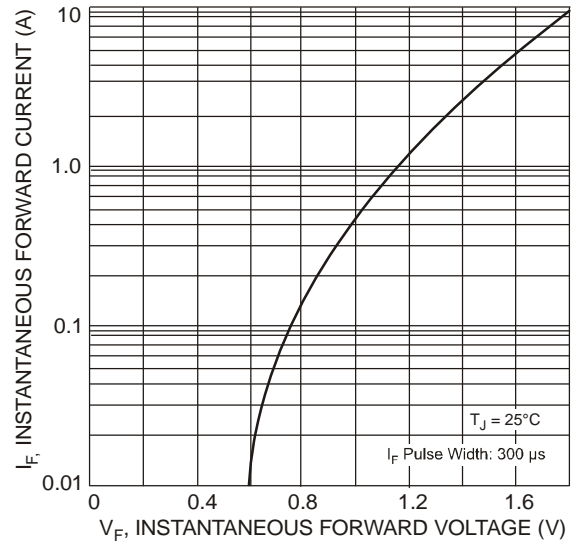


Fig. 2 Typical Forward Characteristics

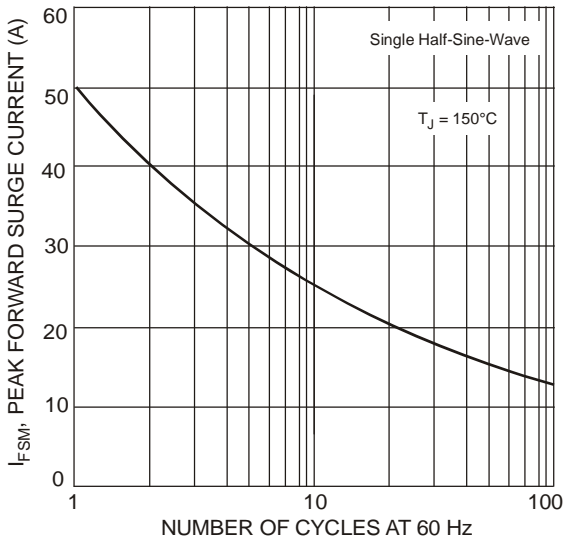


Fig. 3 Forward Surge Current Derating Curve

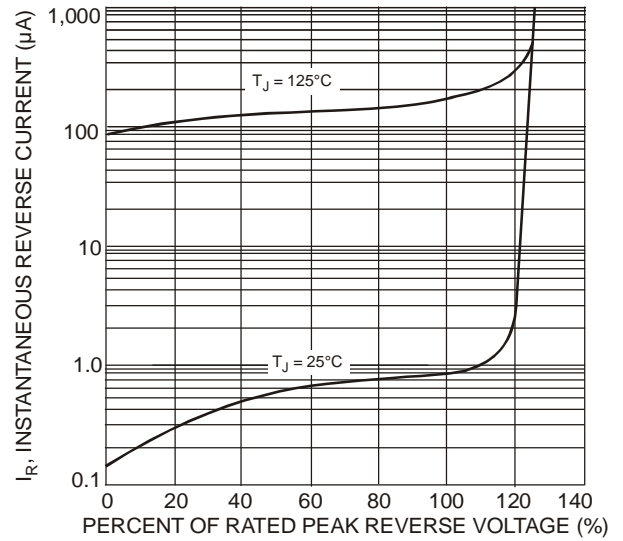
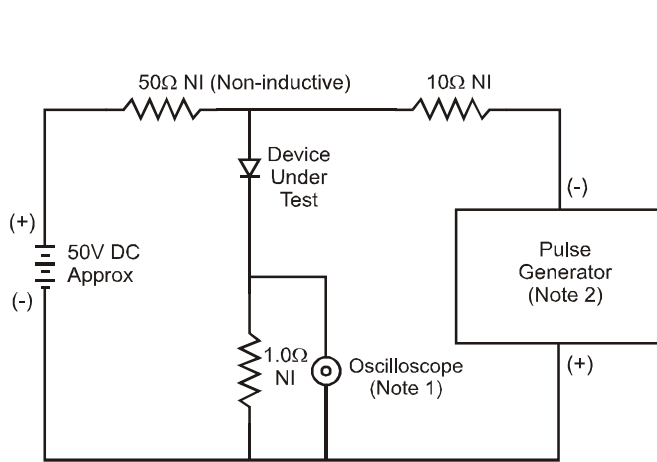


Fig. 4 Typical Reverse Characteristics



- Notes:
1. Rise Time = 7.0ns max. Input Impedance = 1.0MΩ, 22pF.
 2. Rise Time = 10ns max. Input Impedance = 50Ω.

Set time base for 50/100 ns/cm

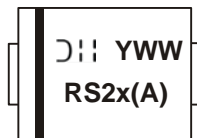
Fig. 5 Reverse Recovery Time Characteristic and Test Circuit

Ordering Information (Note 7)

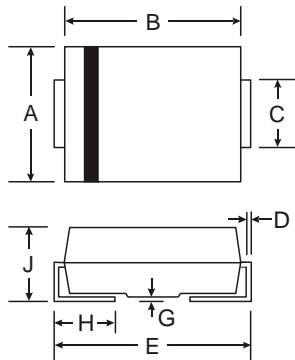
Part Number	Case	Packaging
RS2xA-13-F	SMA	5000/Tape & Reel
RS2x-13-F	SMB	5000/Tape & Reel

*x = Device type, e.g. RS2DA-13-F (SMA package); RS2J-13-F (SMB package).

Notes: 7. For packaging details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

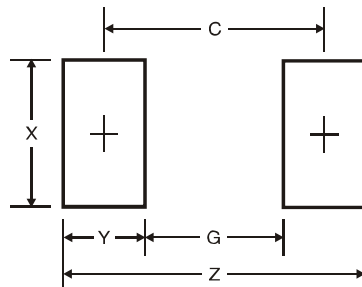
Marking Information


RS2x = Product type marking code, ex: RS2G (SMB package)
 RS2xA = Product type marking code, ex: RS2GA (SMA package)
 DI = Manufacturers' code marking
 YWW = Date code marking
 Y = Last digit of year (ex: 2 for 2002)
 WW = Week code 01 to 52

Package Outline Dimensions


SMA		
Dim	Min	Max
A	2.29	2.92
B	4.00	4.60
C	1.27	1.63
D	0.15	0.31
E	4.80	5.59
G	0.05	0.20
H	0.76	1.52
J	2.01	2.30
All Dimensions in mm		

SMB		
Dim	Min	Max
A	3.30	3.94
B	4.06	4.57
C	1.96	2.21
D	0.15	0.31
E	5.00	5.59
G	0.05	0.20
H	0.76	1.52
J	2.00	2.62
All Dimensions in mm		

Suggested Pad Layout


SMA Dimensions	Value (in mm)
Z	6.5
G	1.5
X	1.7
Y	2.5
C	4.0

SMB Dimensions	Value (in mm)
Z	6.7
G	1.8
X	2.3
Y	2.5
C	4.3

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2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.

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